Vincotech

V23990-P629-L57-PM
datasheet

flowBOOST 0 dual **1200 V / 50 A**

Topology features

- Kelvin Emitter for improved switching performance
- Dual Booster
- Bypass Diode
- Open Emitter configuration
- Temperature sensor

Component features

- Easy paralleling
- High speed switching
- Low switching losses

Housing features

- Base isolation: Al_2O_3
- Clip-in, reliable mechanical connection, qualified for wave soldering
- Convex shaped substrate for superior thermal contact
- Thermo-mechanical push-and-pull force relief
- Solder pin

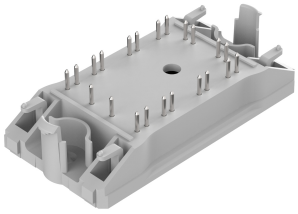
Target applications

- Solar Inverters

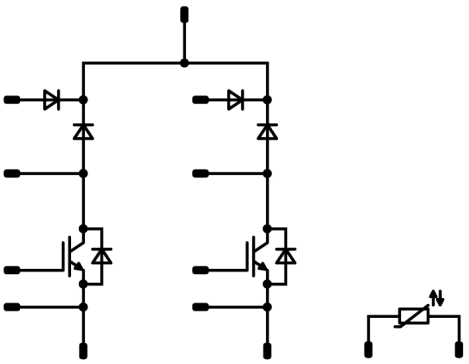
Types

- V23990-P629-L57-PM

flow 0 12 mm housing



Schematic



Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Boost Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$	T_s = 80 °C	54	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		150	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	144	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 800 V	T_j = 150 °C	10	µs
Maximum junction temperature	T_{jmax}			175	°C
Boost Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	41	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		112	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, t_p = 10 ms	T_j = 110 °C	208	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	104	W
Maximum junction temperature	T_{jmax}			175	°C
Boost Sw. Protection Diode					
Peak repetitive reverse voltage	V_{RRM}			1600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	33	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, t_p = 10 ms	T_j = 150 °C	200	A
Surge current capability	I^2t			200	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	44	W
Maximum junction temperature	T_{jmax}			150	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
ByPass Diode					
Peak repetitive reverse voltage	V_{RRM}			1600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	33	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, t_p = 10 ms	T_j = 150 °C	200	A
Surge current capability	I^2t			200	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	44	W
Maximum junction temperature	T_{jmax}			150	°C
Module Properties					
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{jop}			-40…+(T_{jmax} - 25)	°C
Isolation Properties					
Isolation voltage	V_{isol}	DC Test Voltage*	t_p = 2 s	6000	V
Creepage distance				>12,7	mm
Clearance				9,55	mm
Comparative Tracking Index	CTI			≥ 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Boost Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	V_{CE} = V_{GE}			0,0017	25	5,3	5,8	6,3	V
Collector-emitter saturation voltage	V_{CEsat}		15		50	25 125 150	1,78	2,05 2,38 2,46	2,42(1)	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			1	µA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Internal gate resistance	r_g							4		Ω
Input capacitance	C_{ies}	f = 1 Mhz	0	25		25		2770		pF
Reverse transfer capacitance	C_{res}							160		pF
Gate charge	Q_g		±15		0	25		380		nC
Thermal										
Thermal resistance junction to sink(2)	$R_{th(j-s)}$	λ_{paste} = 5,2 W/mK (PTM)						0,66		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 16 Ω R_{goff} = 16 Ω	0/15	700	50	25 125 150		51,52 49,53 49,6		ns
Rise time	t_r					25 125 150		32,23 34,09 34,79		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		445,98 510,38 527,93		ns
Fall time	t_f					25 125 150		17,62 100,59 130,95		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=0,024 µC Q_{rFWD}=0,029 µC Q_{rFWD}=0,029 µC				25 125 150		3,32 3,76 3,92		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		2,78 4,38 4,83		mWs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Boost Diode										
Static										
Forward voltage	V_F				20	25 125 150		1,34 1,52 1,6	1,8(1)	V
Reverse leakage current	I_R	V_r = 1200 V				25		16	2000	µA
Thermal										
Thermal resistance junction to sink(2)	$R_{th(j-s)}$	λ_{paste} = 5,2 W/mK (PTM)						0,91		K/W
Dynamic										
Peak recovery current	I_{RM}	di/dt=1821 A/µs di/dt=1684 A/µs di/dt=1519 A/µs	0/15	700	50	25 125 150		3,9 4,07 4,08		A
Reverse recovery time	t_{rr}					25 125 150		11,62 12,18 11,8		ns
Recovered charge	Q_r					25 125 150		0,024 0,029 0,029		µC
Reverse recovered energy	E_{rec}					25 125 150		$2{,}028\times10^{-3}$ $2{,}585\times10^{-3}$ $2{,}645\times10^{-3}$		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		755,21 928,95 817,42		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Boost Sw. Protection Diode										
Static										
Forward voltage	V_F				8	25 125		0,996 0,907	1,21(1) 1,1(1)	V
Reverse leakage current	I_R	V_r = 1600 V				25			50	µA
Thermal										
Thermal resistance junction to sink(2)	$R_{th(j-s)}$	λ_{paste} = 5,2 W/mK (PTM)						1,59		K/W
ByPass Diode										
Static										
Forward voltage	V_F				8	25 125		0,996 0,907	1,21(1) 1,1(1)	V
Reverse leakage current	I_R	V_r = 1600 V				25			50	µA
Thermal										
Thermal resistance junction to sink(2)	$R_{th(j-s)}$	λ_{paste} = 5,2 W/mK (PTM)						1,59		K/W

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Thermistor										
Static										
Rated resistance	R					25		22		kΩ
Deviation of R25	$\Delta_{R/R}$	R_{25} = 22 kΩ				25	-5		5	%
Deviation of R100		R_{100} = 1486 Ω				100	-12		14	
Power dissipation	P							200		mW
Power dissipation constant	d					25		2		mW/K
B-value	$B_{(25/50)}$	Tol. ±3 %						3950		K
B-value	$B_{(25/100)}$	Tol. ±3 %						3998		K
Vincotech Thermistor Reference									B	

(1) Value at chip level

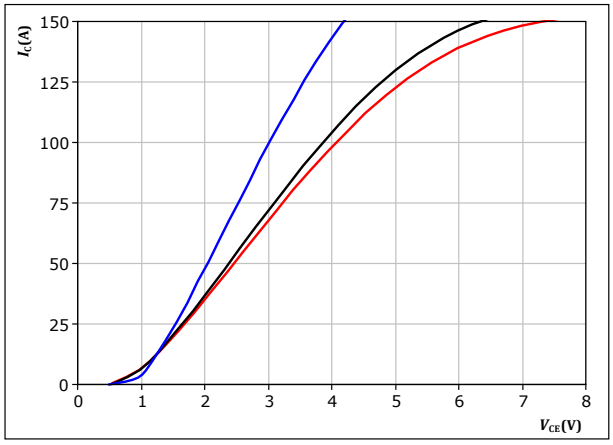
(2) Only valid with pre-applied Vincotech thermal interface material.

Boost Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

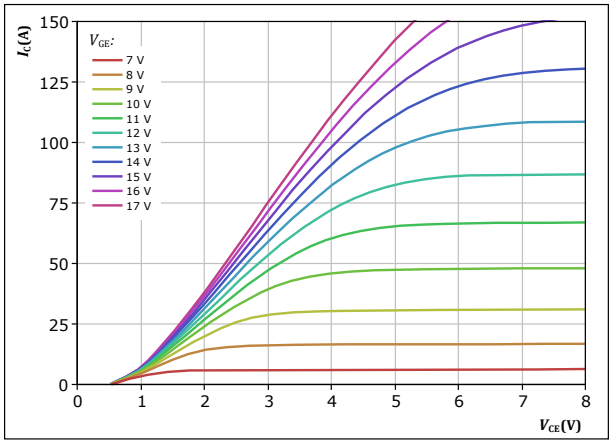


t_p =	250	µs		
V_{GE} =	15	V	T_j:	25 °C
				125 °C
				150 °C

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$



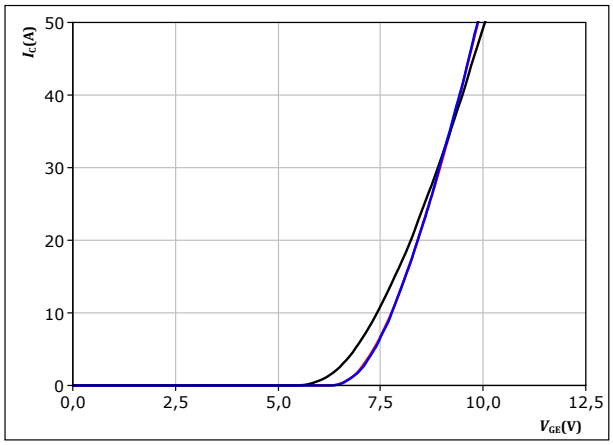
t_p =	250	µs
T_j =	150	°C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

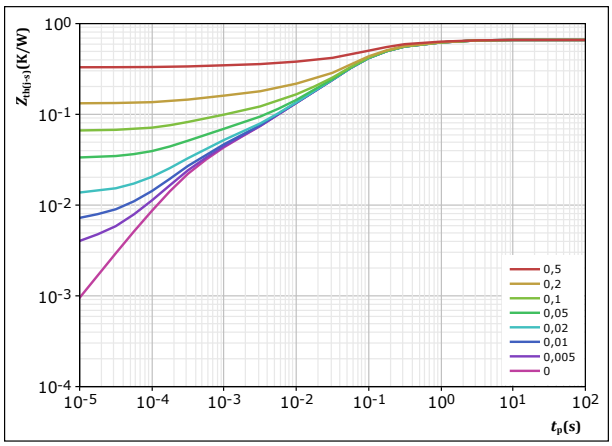


t_p =	250	µs		
V_{CE} =	10	V	T_j:	25 °C
				125 °C
				150 °C

figure 4. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	0,66	K/W

IGBT thermal model values

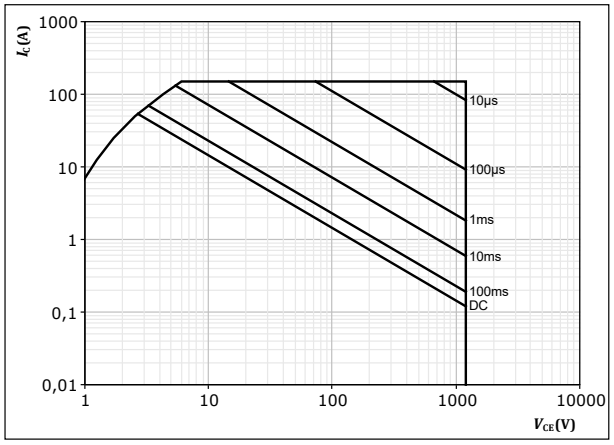
R (K/W)	τ (s)
8,54E-02	1,27E+00
1,79E-01	1,86E-01
3,14E-01	6,03E-02
5,28E-02	4,65E-03
2,90E-02	3,68E-04

Boost Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



D = single pulse

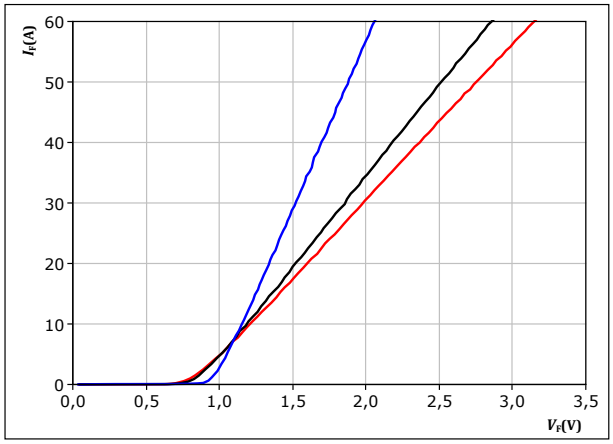
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

Boost Diode Characteristics

figure 6. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



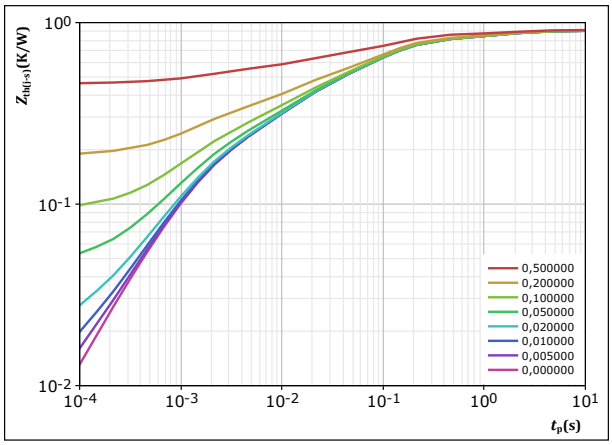
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 7. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 0,91 K/W

FWD thermal model values

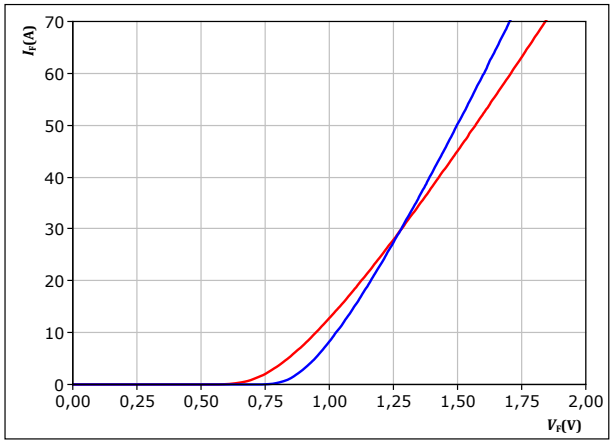
R (K/W)	τ (s)
2,50E-02	3,83E+01
1,15E-01	1,28E+00
4,15E-01	9,60E-02
2,16E-01	1,16E-02
1,49E-01	1,33E-03

Boost Sw. Protection Diode Characteristics

figure 8. **Rectifier**

Typical forward characteristics

$I_F = f(V_F)$



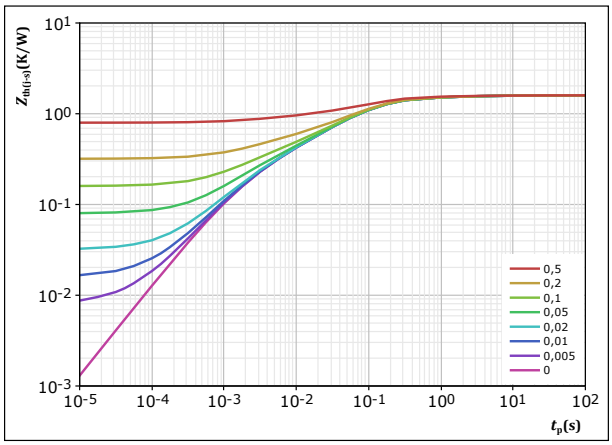
t_p = 250 µs

T_j: 25 °C, 125 °C

figure 9. **Rectifier**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 1,594 K/W

Rectifier thermal model values

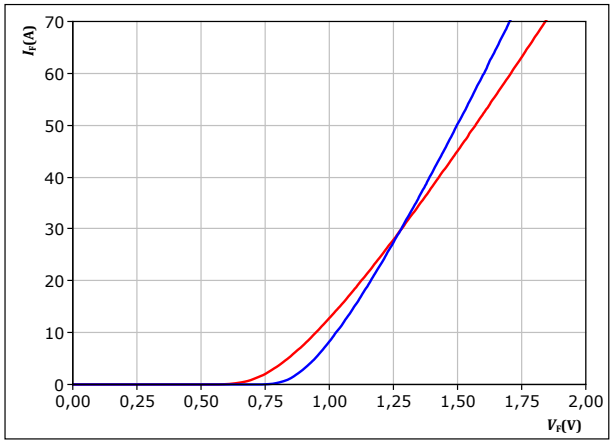
R (K/W)	τ (s)
3,44E-02	9,66E+00
1,12E-01	1,22E+00
5,81E-01	1,45E-01
4,89E-01	5,05E-02
2,38E-01	9,26E-03
1,22E-01	1,79E-03
1,81E-02	7,88E-04

ByPass Diode Characteristics

figure 10. **Rectifier**

Typical forward characteristics

$I_F = f(V_F)$



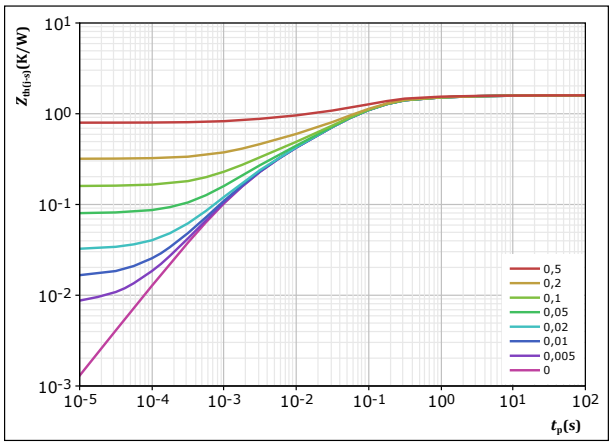
t_p = 250 µs

T_j: 25 °C, 125 °C

figure 11. **Rectifier**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 1,594 K/W

Rectifier thermal model values

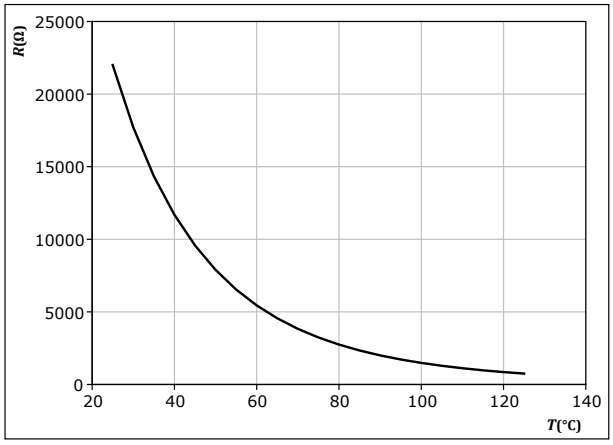
R (K/W)	τ (s)
3,44E-02	9,66E+00
1,12E-01	1,22E+00
5,81E-01	1,45E-01
4,89E-01	5,05E-02
2,38E-01	9,26E-03
1,22E-01	1,79E-03
1,81E-02	7,88E-04

Thermistor Characteristics

figure 12. **Thermistor**

Typical NTC characteristic as function of temperature

$R_T = f(T)$

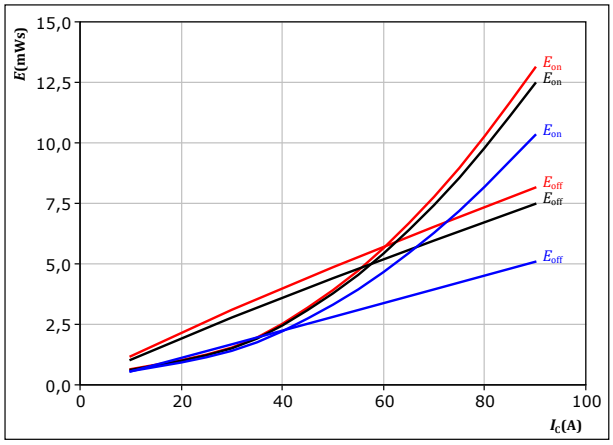


Boost Switching Characteristics

figure 13. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



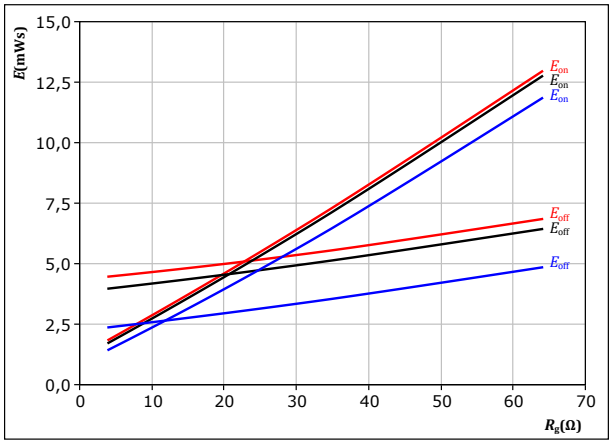
With an inductive load at

V_{CE} =	700	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
R_{gon} =	16	Ω		150 °C
R_{goff} =	16	Ω		

figure 14. **IGBT**

Typical switching energy losses as a function of IGBT turn on gate resistor

$E = f(R_g)$



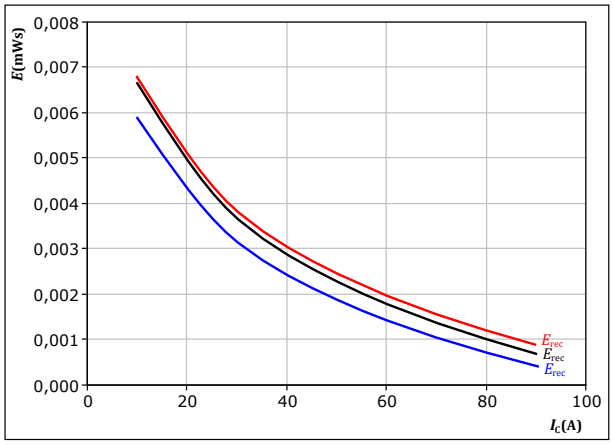
With an inductive load at

V_{CE} =	700	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
I_C =	50	A		150 °C

figure 15. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



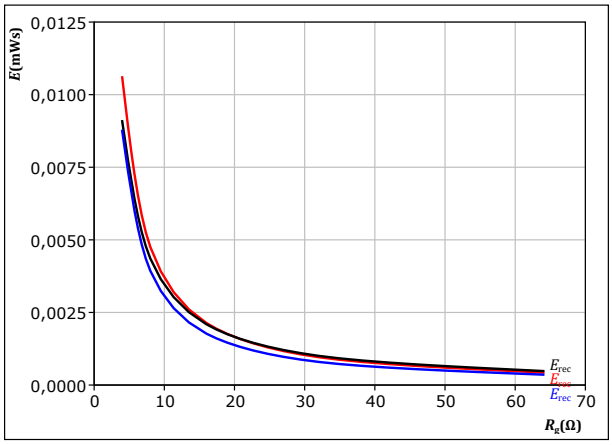
With an inductive load at

V_{CE} =	700	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
R_{gon} =	16	Ω		150 °C

figure 16. **FWD**

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

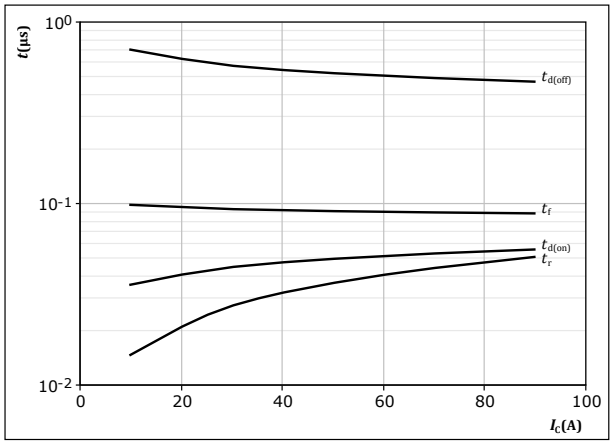
V_{CE} =	700	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
I_C =	50	A		150 °C

Boost Switching Characteristics

figure 17. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



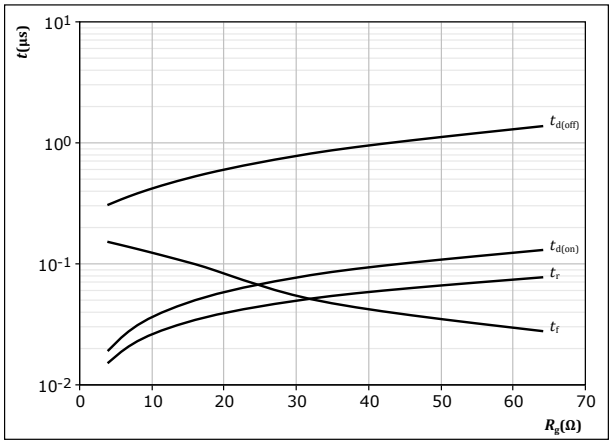
With an inductive load at

T_j =	150	°C
V_{CE} =	700	V
V_{GE} =	0/15	V
R_{gon} =	16	Ω
R_{goff} =	16	Ω

figure 18. **IGBT**

Typical switching times as a function of IGBT turn on gate resistor

$t = f(R_g)$



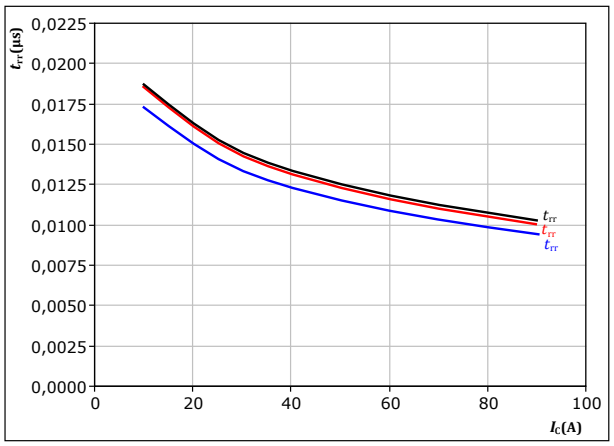
With an inductive load at

T_j =	150	°C
V_{CE} =	700	V
V_{GE} =	0/15	V
I_C =	50	A

figure 19. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



With an inductive load at

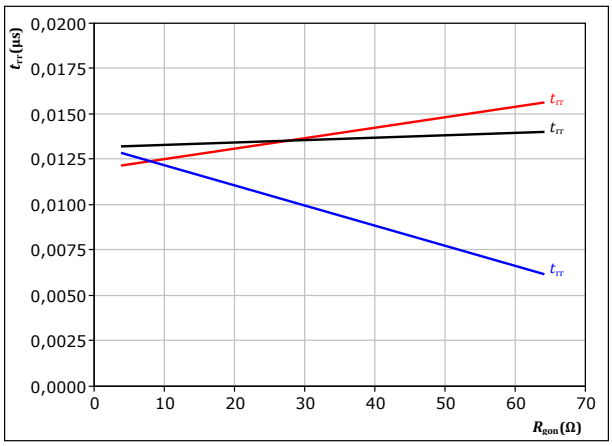
V_{CE} =	700	V
V_{GE} =	0/15	V
R_{gon} =	16	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 20. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



With an inductive load at

V_{CE} =	700	V
V_{GE} =	0/15	V
I_C =	50	A

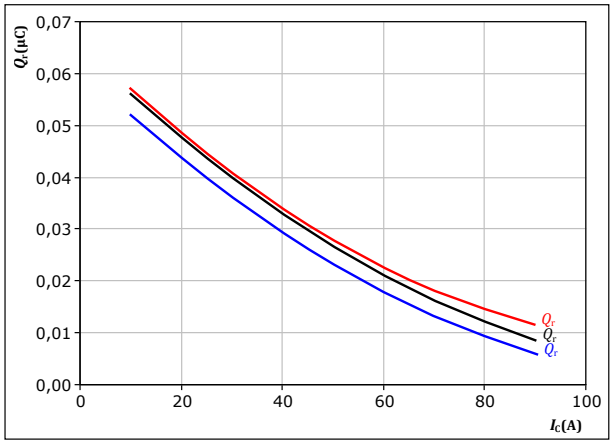
T_j: 25 °C, 125 °C, 150 °C

Boost Switching Characteristics

figure 21. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$



With an inductive load at

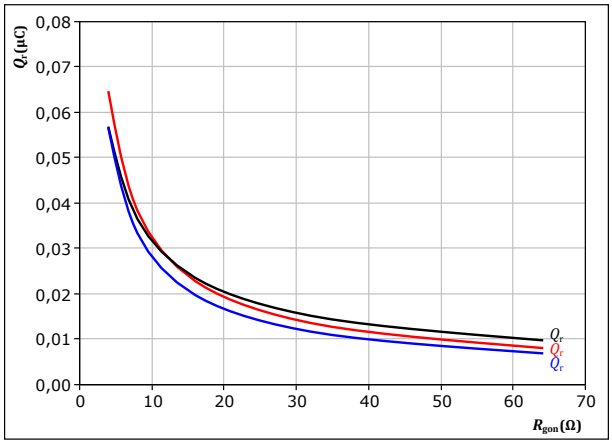
V_{CE} =	700	V
V_{GE} =	0/15	V
R_{gon} =	16	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 22. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$



With an inductive load at

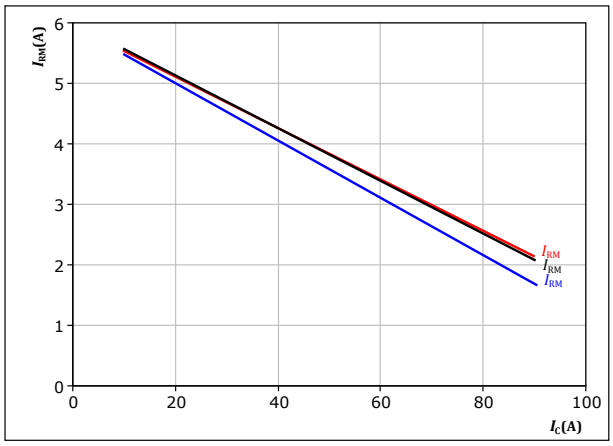
V_{CE} =	700	V
V_{GE} =	0/15	V
I_C =	50	A

T_j: 25 °C, 125 °C, 150 °C

figure 23. **FWD**

Typical peak reverse recovery current as a function of collector current

$I_{RM} = f(I_C)$



With an inductive load at

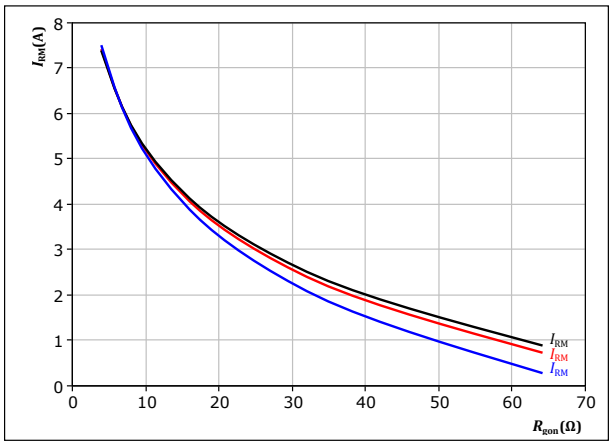
V_{CE} =	700	V
V_{GE} =	0/15	V
R_{gon} =	16	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 24. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



With an inductive load at

V_{CE} =	700	V
V_{GE} =	0/15	V
I_C =	50	A

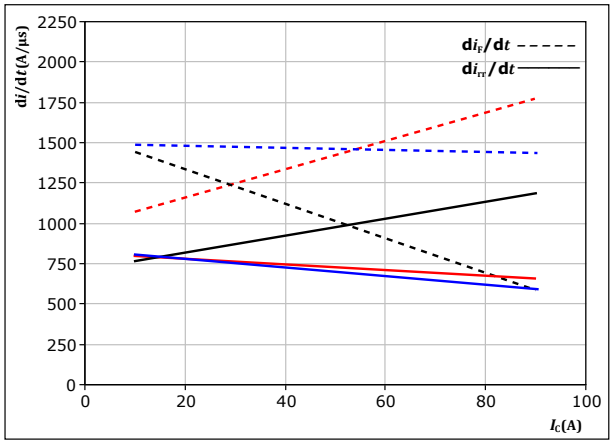
T_j: 25 °C, 125 °C, 150 °C

Boost Switching Characteristics

figure 25. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



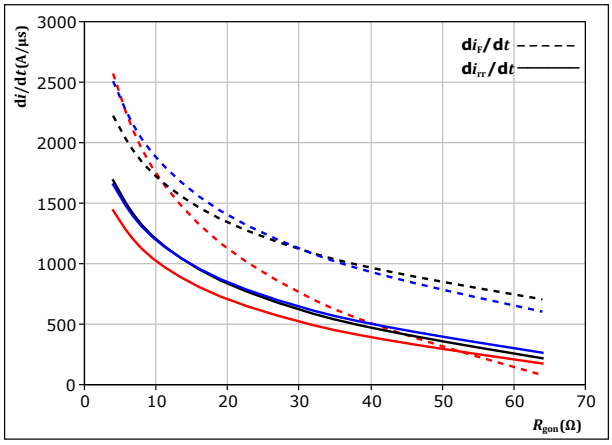
With an inductive load at

V_{CE} =	700	V	T_j: 25 °C
V_{GE} =	0/15	V	125 °C
R_{gon} =	16	Ω	150 °C

figure 26. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

di_F/dt, di_{rr}/dt = f(R_{gon})



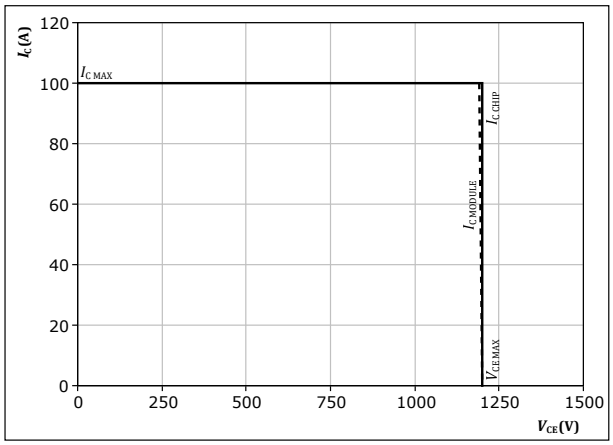
With an inductive load at

V_{CE} =	700	V	T_j: 25 °C
V_{GE} =	0/15	V	125 °C
I_C =	50	A	150 °C

figure 27. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



At

T_j =	150	°C
R_{gon} =	16	Ω
R_{goff} =	16	Ω

Boost Switching Definitions

figure 28. **IGBT**

Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{tEoff} = integrating time for E_{off})

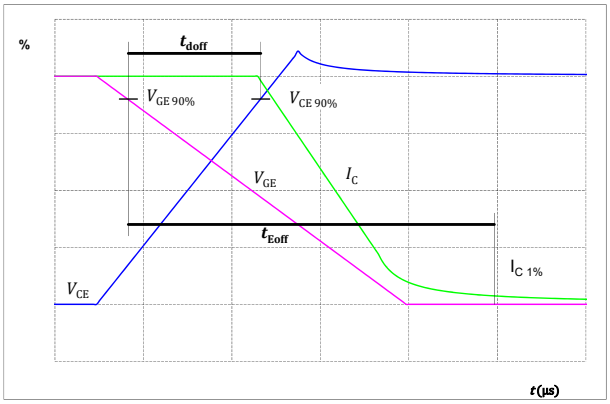


figure 29. **IGBT**

Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})

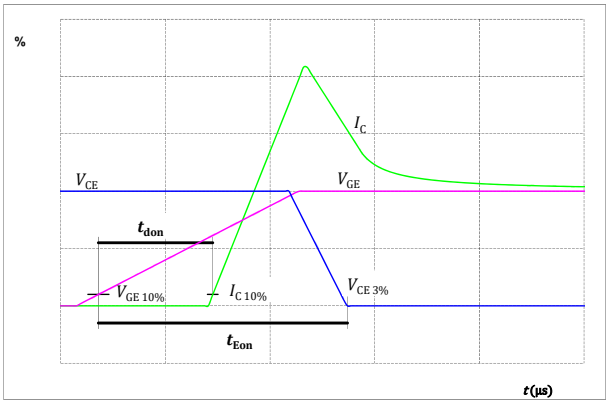


figure 30. **IGBT**

Turn-off Switching Waveforms & definition of t_f

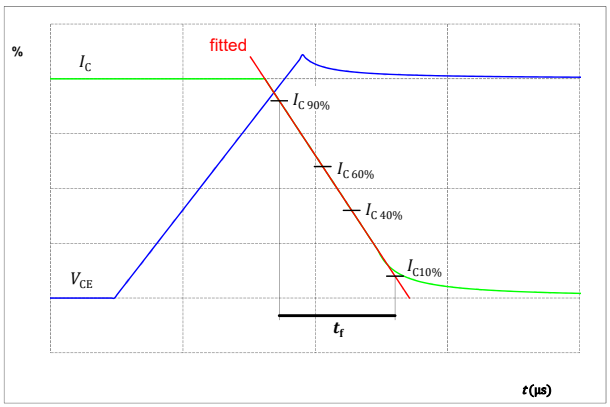
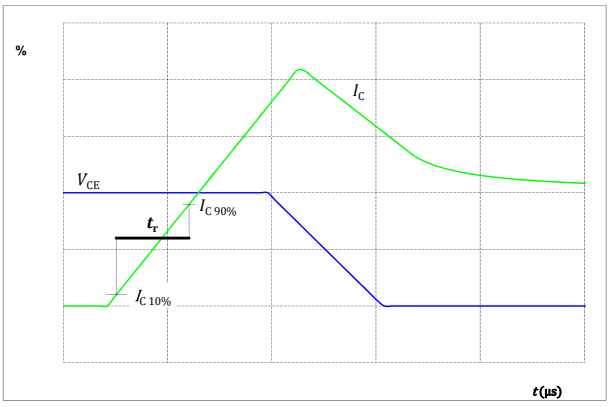


figure 31. **IGBT**

Turn-on Switching Waveforms & definition of t_r



Boost Switching Definitions

figure 32. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

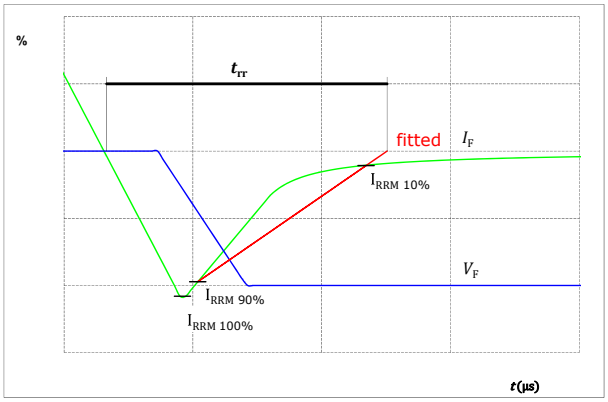
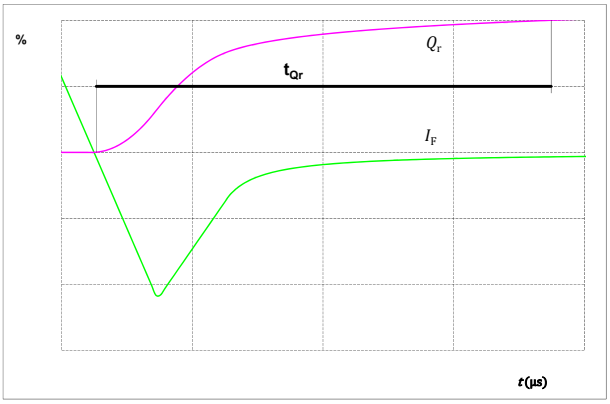


figure 33. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



Ordering Code

Version	Ordering Code
Without thermal paste	V23990-P629-L57-PM
With thermal paste (5,2 W/mK, PTM6000HV)	V23990-P629-L57-/7/-PM

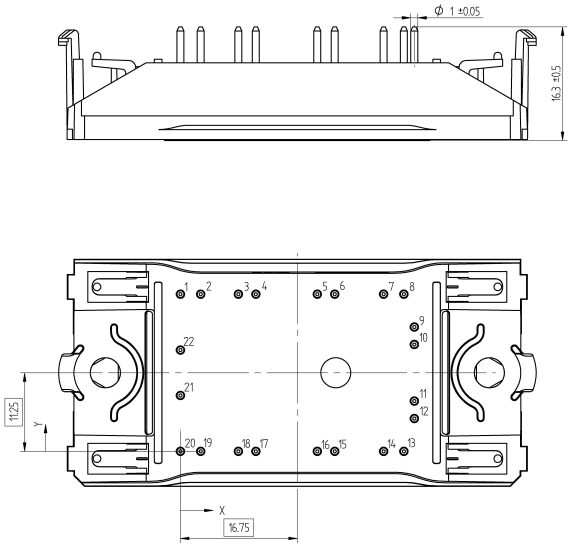
Marking

Text	VIN	Date code	Type&Ver	UL	Lot	Serial
	VIN	WWYY	TTTTTTTVV	UL	LLLLL	SSSS
Datamatrix	**Type&Ver**	**Lot number**	**Serial**	**Date code**		
	TTTTTTTVV	LLLLL	SSSS	WWYY		

Outline

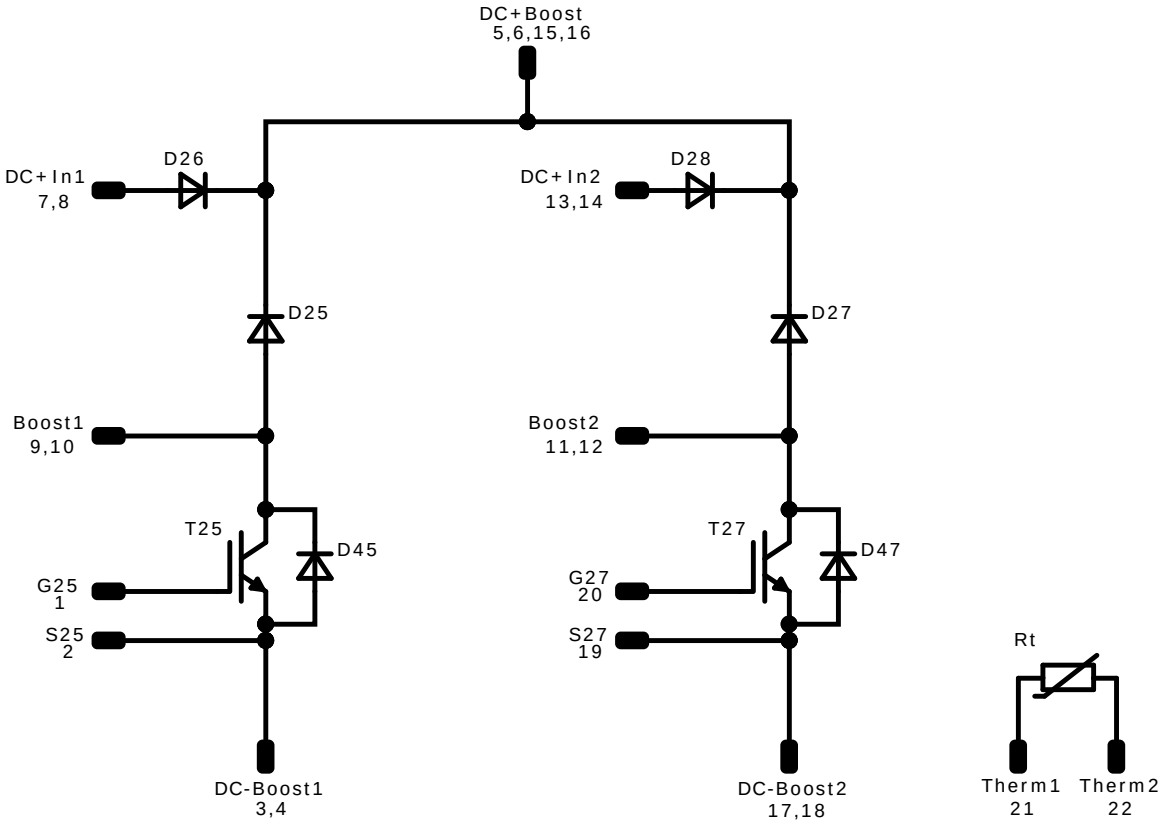
Pin table [mm]

Pin	X	Y	Function
1	0	22,5	G25
2	2,9	22,5	S25
3	8,3	22,5	DC-Boost1
4	10,8	22,5	DC-Boost1
5	19,6	22,5	DC+Boost
6	22,1	22,5	DC+Boost
7	29,1	22,5	DC+In1
8	32	22,5	DC+In1
9	33,5	17,8	Boost1
10	33,5	15,3	Boost1
11	33,5	7,2	Boost2
12	33,5	4,7	Boost2
13	32	0	DC+In2
14	29,1	0	DC+In2
15	22,1	0	DC+Boost
16	19,6	0	DC+Boost
17	10,8	0	DC-Boost2
18	8,3	0	DC-Boost2
19	2,9	0	S27
20	0	0	G27
21	0	8	Therm1
22	0	14,5	Therm2



Tolerance of pinpositions ±0,5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T25, T27	IGBT	1200 V	50 A	Boost Switch	
D25, D27	FWD	1200 V	20 A	Boost Diode	
D45, D47	Rectifier	1600 V	25 A	Boost Sw. Protection Diode	
D26, D28	Rectifier	1600 V	25 A	ByPass Diode	
Rt	NTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 135	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* 0 packages see vincotech.com website.

Package data
Package data for *flow* 0 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is UL 1557 recognized under E192116 up to a junction temperature under switching condition $T_{j,op}$=175°C and up to 3500VAC/1min isolation voltage. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
V23990-P629-L57-PM-D5-14	8 May. 2025	Change Boost Diode. See details in PCN-2025-001	